

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type

SSM3K37CT

- High Speed Switching Applications
- Analog Switch Applications

- 1.5Vdrive
 - Low ON-resistance
- $R_{DS(ON)} = 5.60\ \Omega\ (\text{max})\ (@V_{GS} = 1.5\ \text{V})$
 $R_{DS(ON)} = 4.05\ \Omega\ (\text{max})\ (@V_{GS} = 1.8\ \text{V})$
 $R_{DS(ON)} = 3.02\ \Omega\ (\text{max})\ (@V_{GS} = 2.5\ \text{V})$
 $R_{DS(ON)} = 2.20\ \Omega\ (\text{max})\ (@V_{GS} = 4.5\ \text{V})$

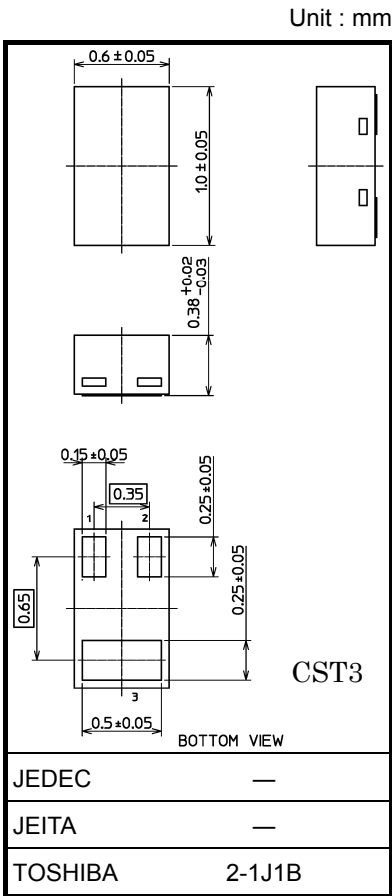
Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-Source voltage		V_{DSS}	20	V
Gate-Source voltage		V_{GSS}	± 10	V
Drain current	DC	I_D	200	mA
	Pulse	I_{DP}	400	
Power dissipation		$P_D(\text{Note1})$	100	mW
Channel temperature		T_{ch}	150	°C
Storage temperature range		T_{stg}	-55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

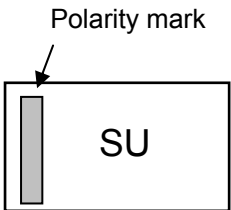
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook (“Handling Precautions”/“Derating Concept and Methods”) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Mounted on FR4 board
(10 mm × 10 mm × 1.0 mm, Cu Pad: 100 mm²)

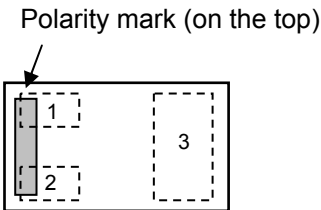


Weight: 0.75mg(typ.)

Marking(top view)

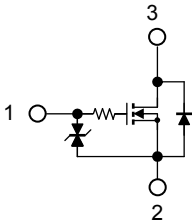


Pin Condition (top view)



- 1. Gate
 - 2. Source
 - 3. Drain
- *Electrodes: On the bottom

Equivalent Circuit



Start of commercial production
2010-11

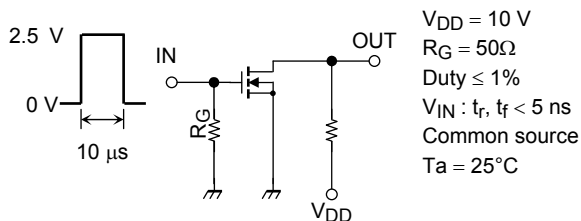
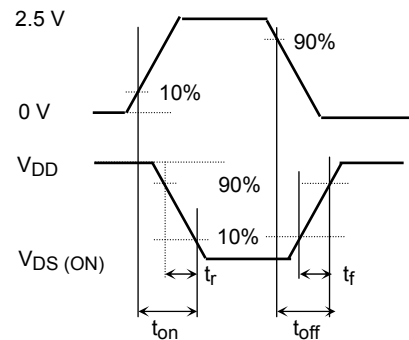
Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 1 \text{ mA}$, $V_{GS} = 0 \text{ V}$	20	—	—	V
	$V_{(BR)DSX}$	$I_D = 1 \text{ mA}$, $V_{GS} = -10 \text{ V}$	12	—	—	
Drain cut-off current	I_{DSS}	$V_{DS} = 20 \text{ V}$, $V_{GS} = 0 \text{ V}$	—	—	1	μA
Gate leakage current	I_{GSS}	$V_{GS} = \pm 10 \text{ V}$, $V_{DS} = 0 \text{ V}$	—	—	± 1	μA
Gate threshold voltage	V_{th}	$V_{DS} = 3 \text{ V}$, $I_D = 1 \text{ mA}$	0.35	—	1.0	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 3 \text{ V}$, $I_D = 100 \text{ mA}$ (Note2)	0.14	0.28	—	S
Drain-source ON-resistance	$R_{DS(ON)}$	$I_D = 100 \text{ mA}$, $V_{GS} = 4.5 \text{ V}$ (Note2)	—	1.65	2.20	Ω
		$I_D = 50 \text{ mA}$, $V_{GS} = 2.5 \text{ V}$ (Note2)	—	2.16	3.02	
		$I_D = 20 \text{ mA}$, $V_{GS} = 1.8 \text{ V}$ (Note2)	—	2.66	4.05	
		$I_D = 10 \text{ mA}$, $V_{GS} = 1.5 \text{ V}$ (Note2)	—	3.07	5.60	
Input capacitance	C_{iss}	$V_{DS} = 10 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$	—	12	—	pF
Output capacitance	C_{oss}		—	5.5	—	
Reverse transfer capacitance	C_{rss}		—	4.1	—	
Switching time	Turn-on time	t_{on}	$V_{DD} = 10 \text{ V}$, $I_D = 100 \text{ mA}$	—	18	ns
	Turn-off time	t_{off}	$V_{GS} = 0 \text{ to } 2.5 \text{ V}$, $R_G = 50 \Omega$	—	36	
Drain-Source forward voltage	V_{DSF}	$I_D = -200 \text{ mA}$, $V_{GS} = 0 \text{ V}$ (Note2)	—	-0.89	-1.2	V

Note2: Pulse test

Switching Time Test Circuit

(a) Test Circuit

(b) V_{IN} (c) V_{OUT}

Precaution

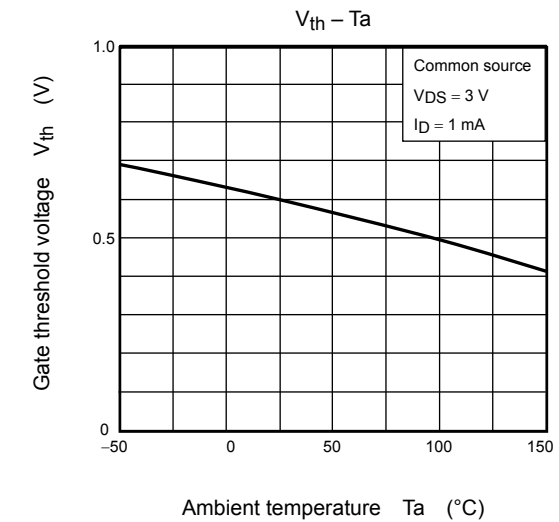
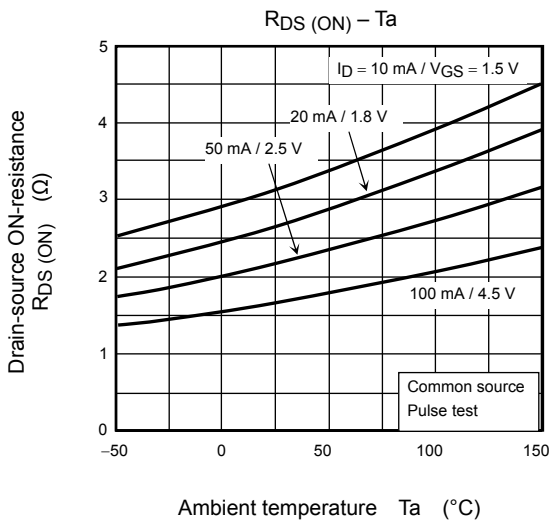
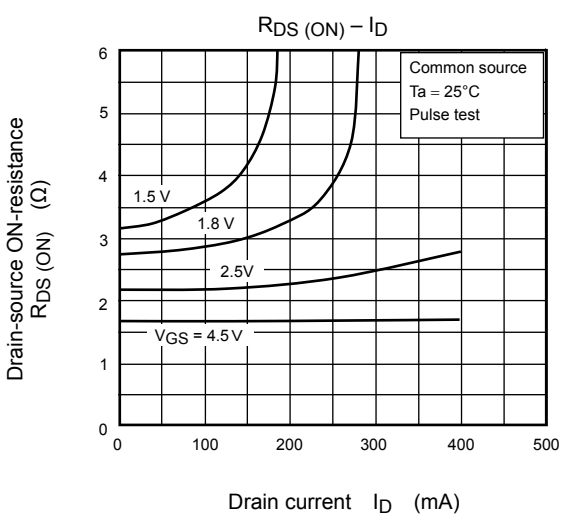
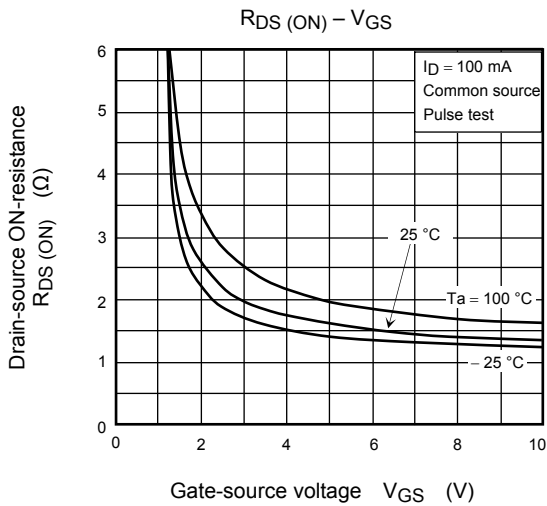
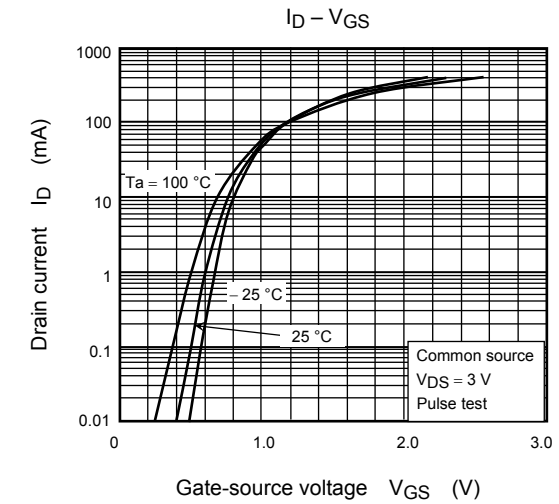
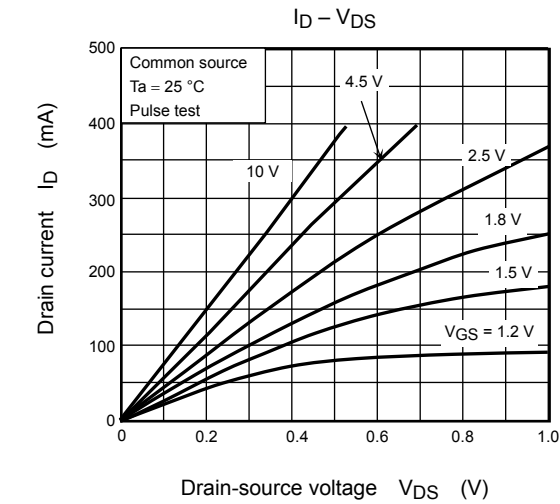
Let V_{th} be the voltage applied between gate and source that causes the drain current (I_D) to be low (1mA for the SSM3K37CT). Then, for normal switching operation, $V_{GS(on)}$ must be higher than V_{th} , and $V_{GS(off)}$ must be lower than V_{th} . This relationship can be expressed as: $V_{GS(off)} < V_{th} < V_{GS(on)}$.

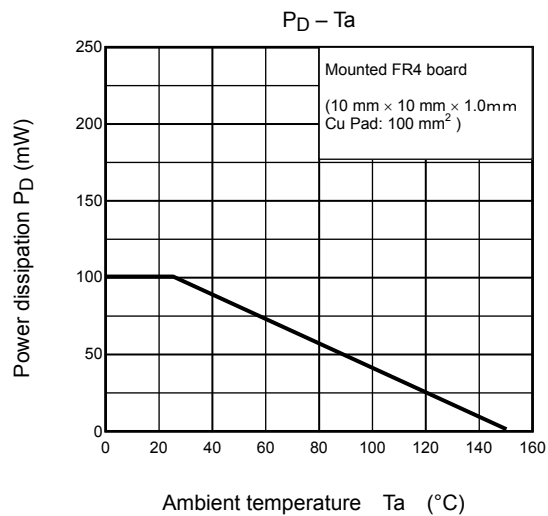
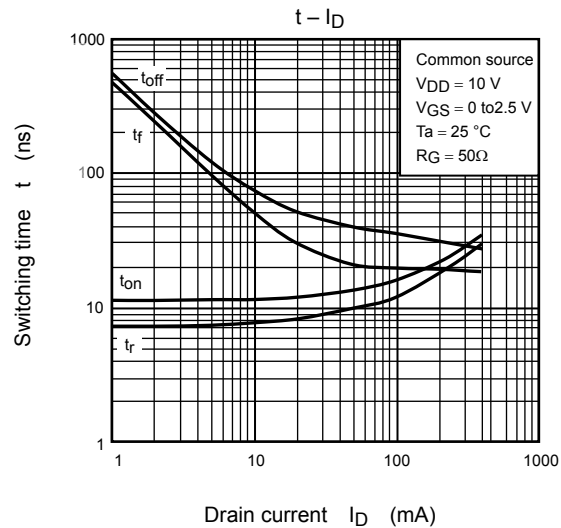
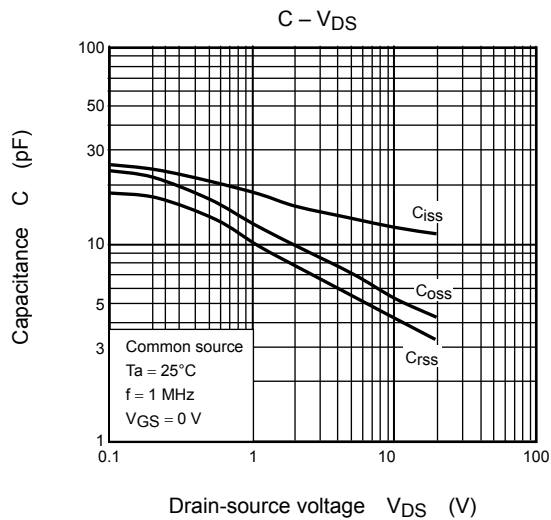
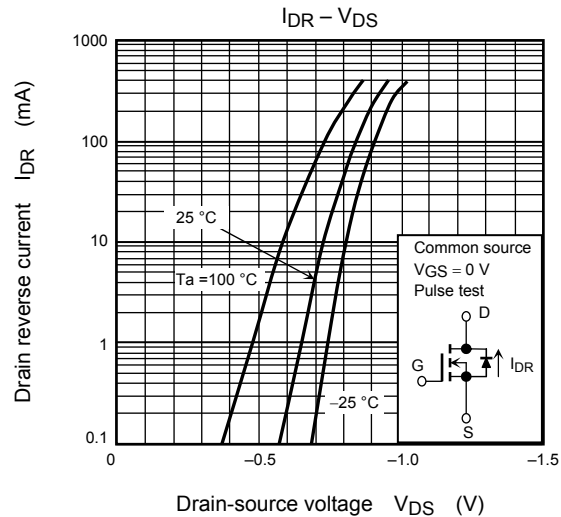
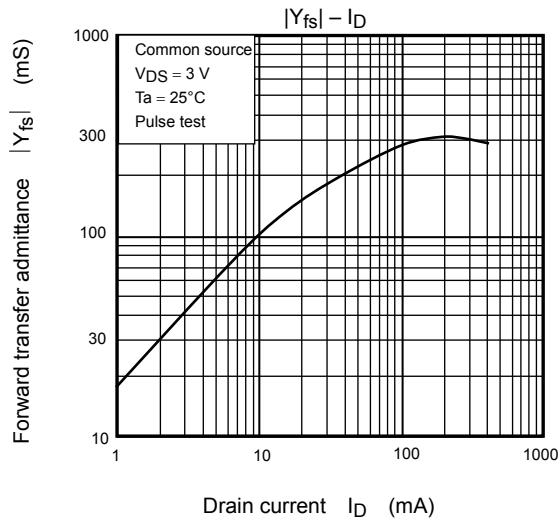
Take this into consideration when using the device.

Handling Precaution

When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

Thermal resistance $R_{th(ch-a)}$ and power dissipation P_D vary depending on board material, board area, board thickness and pad area. When using this device, please take heat dissipation into consideration





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